

International Conference and Exhibition
on
Device Packaging

www.imaps.org/devicepackaging

Radisson Fort McDowell Resort & Casino
Scottsdale/Fountain Hills, Arizona - USA
March 9 - 12, 2009



Sponsored by
IMAPS

International Microelectronics And Packaging Society
Bringing Together the Entire Microelectronics Supply Chain!

Abstract Deadline Extended:
December 5, 2008

Announcement and Call for Abstracts

**Topical Workshop on
Flip Chip Technologies**

This workshop is being held as a part of the Device Packaging Conference

Technical Chairs:

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Flip Chip Technologies Organizing Committee:

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Flip Chip Technologies Workshop Focus: The objective of the Flip Chip Workshop is to have a unique forum that brings together scientists, engineers, manufacturing, academia, and business people from around the world who have been working in the area of Flip Chip packaging and associated Pb-Free implementation challenges. This workshop has been specifically organized to allow for the presentation and debate of some of the latest and hottest technologies out there related to Flip Chip. **Abstracts are being requested on the following topics:**

- Pb-Free Flip Chip Implementations including Assembly, Bumping, Testing, Reliability
- Materials & Processes Improvements and Issues
 - Wafer Saw
 - Substrates
 - Die Attach
 - Underfill,
 - Thermal Interface Materials
 - Lids and Lid Attach
 - Sphere Attach
- Wafer bumping materials and processes including Pb-Free / Green flip chip bumping, Copper Pillar, fine pitch bumping
- Design for flip chip advancements in Substrates and Board Technologies, Substrate Design, Layout and Simulation Tools, Thermo-mechanical modeling.
- Non-solder based flip chips
- Reliability including Electro-migration and Inter-metallic effects, temperature cycling, HAST, HTS,
- End use Applications (i.e., OEM products)
- FC Applications

Those wishing to present in the Flip Chip Technologies sector of the Device Packaging Conference must submit a 200-300 word abstract electronically **by December 5, 2008**, using the on-line submittal form at: www.imaps.org/abstracts.htm. No formal technical paper is required. A reproduction-ready two- to six-page concise summary with text (figures and graphs included if necessary) will be required for the abstract booklet on Friday, January 30, 2009. A post-conference CD containing the full presentation material as supplied by authors will be mailed 15 business days after the event to all attendees. Please contact Jackki Morris-Joyner by email at jmorris@imaps.org or by phone at 305-382-8433 if you have questions.

Device Packaging Exhibit and Technology Show: IMAPS will hold a concurrent exhibition for vendors and suppliers who support the many aspects of Flip Chip Technologies. This venue features an ideal atmosphere to showcase your products and services to key decision making professionals in the industry. Full 8' by 10' exhibit spaces will be available. To reserve booth space please fill out the on-line submittal form before February 4, 2009 at: www.imaps.org/devicepackaging or contact Ann Bell by email at abell@imaps.org or by phone at 202-548-8717.

Device Packaging Professional Development Courses (PDCs): For those wishing to broaden their knowledge of device packaging, a selection of half-day courses will be offered on Monday, March 9th, preceding the technical conference. If you would like to participate as an instructor, please submit a description of your short course to Jackki Morris-Joyner by email at jmorris@imaps.org **no later than December 5, 2008.**